

**SURFACE MOUNT GLASS PASSIVATED  
HIGH EFFICIENCY SILICON RECTIFIER**  
VOLTAGE 1200 Volts CURRENT 1.0 Ampere

**FEATURES**

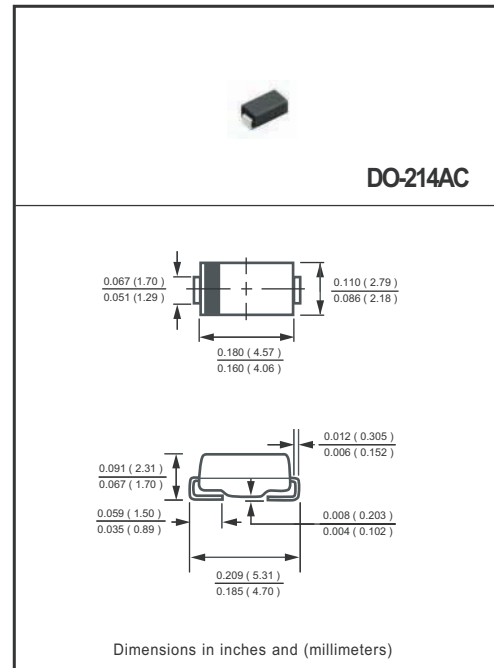
- \* Glass passivated device
- \* Ideal for surface mounted applications
- \* Low leakage current
- \* Metallurgically bonded construction
- \* Mounting position: Any
- \* Weight: 0.057 gram
- \* P/N suffix V means AEC-Q101 qualified, e.g:HFM1012V
- \* P/N suffix V means Halogen-free

**MECHANICAL DATA**

- \* Epoxy: Device has UL flammability classification 94V-O

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25 °C ambient temperature unless otherwise specified.  
resistive or inductive load.



**MAXIMUM RATINGS (@ TA=25 °C unless otherwise noted)**

RATINGS	SYMBOL	HFM1012	UNITS
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	1200	Volts
Maximum RMS Voltage	$V_{RMS}$	840	Volts
Maximum DC Blocking Voltage	$V_{DC}$	1200	Volts
Maximum Average Forward Rectified Current at $T_J = 125^\circ\text{C}$	$I_O$	1.0	Amps
Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	30	Amps
Current Squared Time	$I^2t$	3.7	$\text{A}^2/\text{Sec}$
Typical Thermal Resistance (Note 1)	$R_{\theta JL}$	27	$^\circ\text{C}/\text{W}$
Typical Thermal Resistance (Note 1)	$R_{\theta JA}$	75	$^\circ\text{C}/\text{W}$
Typical Junction Capacitance (Note 2)	$C_J$	12	pF
Operating Temperature Range	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to + 150	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS (@TA=25 °C unless otherwise noted)**

CHARACTERISTICS	SYMBOL	HFM1012	UNITS
Maximum Instantaneous Forward Voltage at 1.0A DC	$V_F$	1.9	Volts
Maximum Full Load Reverse Current, Full cycle Average $T_A = 55^\circ\text{C}$	$I_R$	50	$\mu\text{A}$
Maximum Average Reverse Current at Rated DC Blocking Voltage @ $T_A = 25^\circ\text{C}$		5	$\mu\text{A}$
@ $T_A = 150^\circ\text{C}$		200	$\mu\text{A}$
Maximum Reverse Recovery Time (Note 3)	$t_{rr}$	75	nSec

- NOTES : 1. Thermal Resistance : Mounted on PCB.  
2. Measured at 1 MHz and applied reverse voltage of 4.0 volts.  
3. Test Conditions:  $I_F = 0.5\text{A}$ ,  $I_R = -1.0\text{A}$ ,  $I_{RR} = -0.25\text{A}$ .

## RATING AND CHARACTERISTICS CURVES ( HFM1012 )

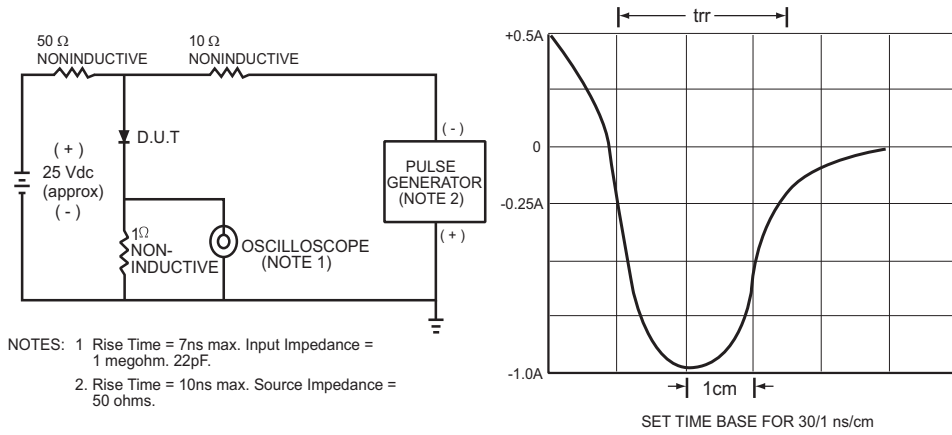


FIG.1 TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

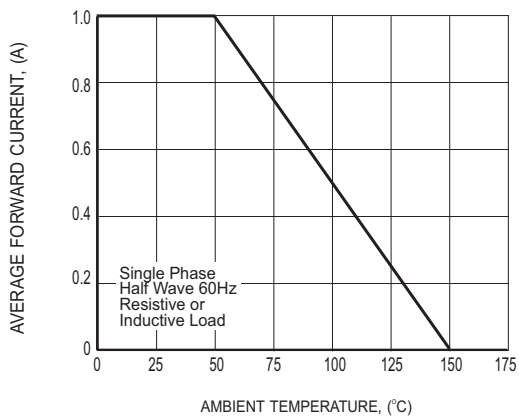


FIG.2 TYPICAL FORWARD CURRENT DERATING CURVE

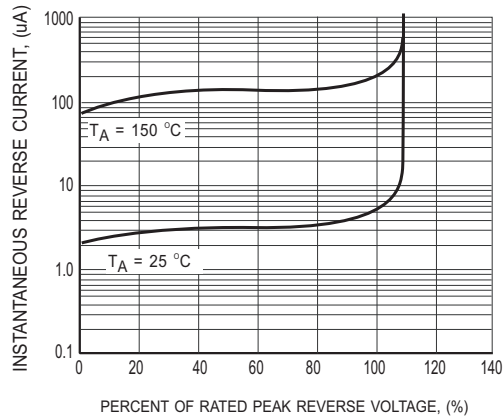
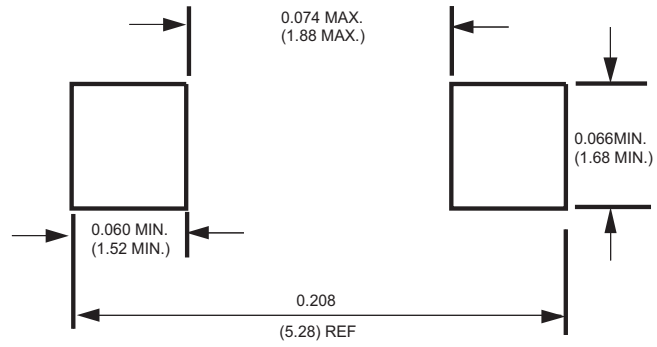


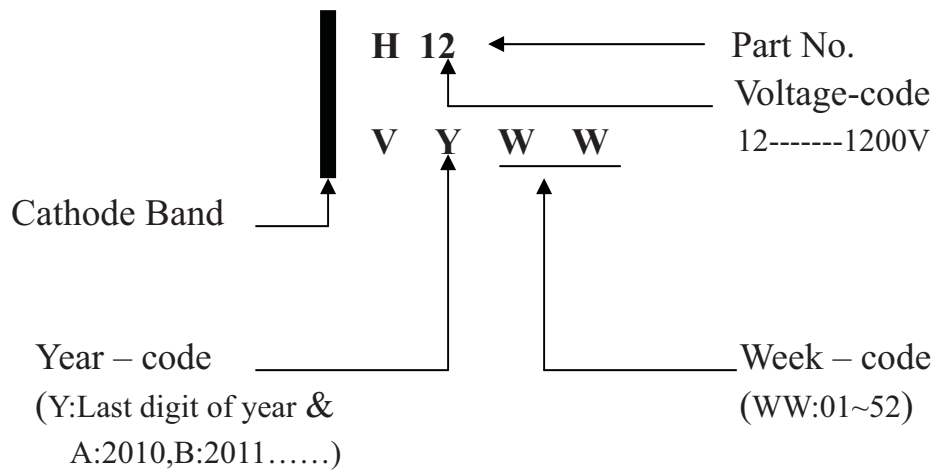
FIG.3 MAXIMUM REVERSE CHARACTERISTICS

## Mounting Pad Layout



Dimensions in inches and (millimeters)

## Marking Description



## PACKAGING OF DIODE AND BRIDGE RECTIFIERS

### REEL PACK

PACKAGE	PACKING CODE	EA PER REEL	EA PER INNER BOX	COMPONENT SPACE (mm)	TAPE SPACE (mm)	REEL DIA (mm)	CARTON SIZE (mm)	EA PER CARTON	GROSS WEIGHT(Kg)
SMA	-W	7,500	15,000	---	---	330	360*355*360	120,000	15.2

PACKAGE	PACKING CODE	EA PER REEL	EA PER INNER BOX	COMPONENT SPACE (mm)	TAPE SPACE (mm)	REEL DIA (mm)	CARTON SIZE (mm)	EA PER CARTON	GROSS WEIGHT(Kg)
SMA	-T	2,000	8,000	---	---	178	390*205*310	64,000	7.8

# REEL TAPING SPECIFICATIONS FOR SURFACE MOUNT DEVICES-FLAT MELF ( SMA/SMB/SMC )

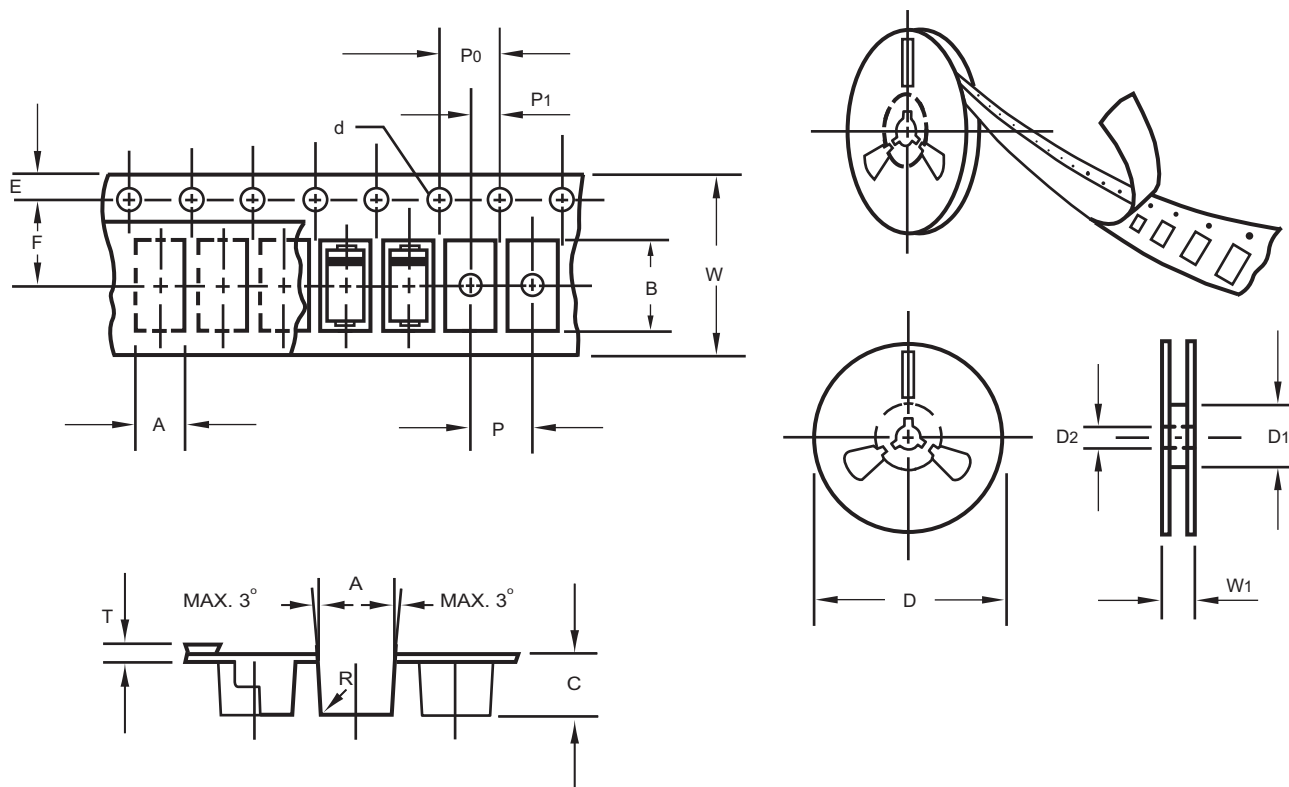


Fig.: Configuration of FLAT MELF TAPING  
( SMA/SMB/SMC )

ITEM	SYMBOL	DO214AC (SMA) mm(inch)	DO214AA (SMB) mm(inch)	DO214AB (SMC) mm(inch)
Carrier width	A	2.6 ± 0.15 (0.102 ± 0.006)	3.65 ± 0.1 (0.144 ± 0.004)	6.0 ± 0.1 (0.236 ± 0.004)
Carrier length	B	5.15 ± 0.15 (0.203 ± 0.006)	5.69 ± 0.1 (0.224 ± 0.004)	8.30 ± 0.1 (0.327 ± 0.004)
Carrier depth	C	2.3 ± 0.15 (0.091 ± 0.006)	2.67 ± 0.1 (0.105 ± 0.004)	2.5 ± 0.1 (0.098 ± 0.004)
Sprocket hole	d	1.5 ± 0.1 (0.059 ± 0.004)	1.5 ± 0.1 (0.059 ± 0.004)	1.5 ± 0.1 (0.059 ± 0.004)
Reel outside diameter	D	178 ± 2.0 (7.0 ± 0.079)	178 ± 2.0 (7.0 ± 0.079)	178 ± 2.0 (7.0 ± 0.079)
Reel inner diameter	D1	50 Min.	50 Min.	50 Min.
Feed hole diameter	D2	13 ± 0.5 (0.512 ± 0.020)	13 ± 0.5 (0.512 ± 0.020)	13 ± 0.5 (0.512 ± 0.020)
Sprocket hole position	E	1.5 ± 0.1 (0.059 ± 0.004)	1.5 ± 0.1 (0.059 ± 0.004)	1.5 ± 0.1 (0.059 ± 0.004)
Punch hole position	F	5.65 ± 0.05 (0.222 ± 0.002)	5.65 ± 0.05 (0.222 ± 0.002)	7.65 ± 0.05 (0.301 ± 0.002)
Punch hole pitch	P	4.0 ± 0.1 (0.157 ± 0.004)	8.0 ± 0.1 (0.315 ± 0.004)	8.0 ± 0.1 (0.315 ± 0.004)
Sprocket hole pitch	P0	4.0 ± 0.1 (0.157 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)
Embossment center	P1	2.0 ± 0.1 (0.079 ± 0.004)	2.0 ± 0.1 (0.079 ± 0.004)	4.0 ± 0.1 (0.157 ± 0.004)
Total tape thickness	T	0.30 ± 0.05 (0.012 ± 0.002)	0.6 Max.	0.6 Max.
Tape width	W	12.0 ± 0.2 (0.472 ± 0.008)	12.0 ± 0.2 (0.472 ± 0.008)	16.0 ± 0.2 (0.630 ± 0.008)
Reel width	W1	16.8 ± 2.0 (0.661 ± 0.079)	16.8 ± 2.0 (0.661 ± 0.079)	24.0 ± 2.0 (0.945 ± 0.079)

Note: 1.Devices are packed in accordance with EIA standard RS-481-A and specification given above.  
2.Available on 7 inch ( 1500 ct. ) or 13 inch ( 5000 ct. ) diameter reels.

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